What is claimed is:

1. A connection component comprising:

a dielectric element having a first surface and a second surface;

conductive pads on the first surface of the dielectric element, each conductive pad having a center;

conductive vias electrically connected to said conductive pads and extending toward the second surface of said dielectric element, each said via having an opening at one of said conductive pads, wherein at least one of the via openings is offset from the center of at least one of said conductive pads.

- 2. The connection component as claimed in claim 1, wherein each said via has a center, and wherein the centers of one or more of said vias are offset from the centers of one or more of said conductive pads.
- 3. The method as claimed in claim 1, wherein each said via has a center, and wherein the centers of said vias are offset from the centers of said conductive pads.
- 4. The method as claimed in claim 1, wherein each said via has a closed end opposite the opening thereof and adjacent the second surface of said dielectric element.
- 5. The connection component as claimed in claim 1, further comprising a fusible mass attached to the first surface of said dielectric element adjacent to the at least one offset via opening.
- 6. The connection component as claimed in claim 1, wherein said dielectric element is a flexible dielectric sheet.
- 7. The connection component as claimed in claim 1, further comprising conductive traces overlying the second surface of said dielectric element, said conductive traces

being electrically interconnected with said conductive vias.

- 8. The connection component as claimed in claim 8, wherein said vias extend in a direction that intersects planes defined by the first and second surfaces of said dielectric element.
- 9. The connection component as claimed in claim 1, wherein said conductive vias comprise a conductive metal.
- 10. The connection component as claimed in claim 1, wherein said conductive vias are covered by a conductive polymer.